ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC Bannockl	ourn Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and I					ials and M	fg Informa	tion		
upplier Information														
Company name* Cor			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi								2024-0			24-04-19			
ntact Name Title - Contact					Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - F			le - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards	Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		mber Mfr Item Name			Effective Date	fective Date Version Manufacturing Site		Ianufacturing Site		Weight*	UOM	Unit Type	
	ATP112	TP112-TL-H PCH 4V DRIVE SEI		SERIES		2024-04-19	CNG		NG		262.59	mg	Each	
Anufacturing Proccess Information	ation							·						
Terminal Plating / Grid Array M	laterial 7	rial Terminal Base Alloy		J-STD-020 MSI	L Rating	Peak Proce	ocess Body Temperature Max Time at Peak		. Tempera	ure Num	ber of Reflow Cyc	eles		
contains Bi CU Alloy		CU Alloy	1			260 C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).								
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach	2.85	mg	Supplier	Silver (Ag)	7440-22-4		0.057	mg
			А	Lead (Pb)	7439-92-1	7a	2.6505	mg
			Supplier	Tin (Sn)	7440-31-5		0.1425	mg
Lead Frame	148.06	mg	Supplier	Tin (Sn)	7440-31-5		0.2221	mg
			Supplier	Copper (Cu)	7440-50-8		147.8379	mg
Mold Compound-Black	106.72	mg		Phenolic Resin	proprietary data		2.668	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		8.8044	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5336	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		94.1804	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5336	mg
Plating	3.3	mg	В	Bismuth (Bi)	7440-69-9		0.0198	mg
			Supplier	Tin (Sn)	7440-31-5		3.2802	mg